

REMARKS

This application has been carefully reviewed in light of the Office Action dated June 27, 2003 (Paper No. 8). Claims 5, 8 and 9 are in the application, with Claim 5 being the sole independent claim. Favorable consideration and early passage to issue are respectfully requested.

The Office Action Summary indicates that corrected drawings are required. However, Applicant already submitted corrected drawings with the Letter Transmitting Formal Drawings dated April 3, 2003. Accordingly, it is respectfully requested that the next Office communication acknowledge acceptance of the formal drawings.

Claims 5, 6 and 8 were rejected under 35 U.S.C. §103(a) over Applicant's Fig. 7 in view of Japan 56-130978 (Yonezawa) and U.S. Patent No. 5,132,772 (Fetty); and Claim 9 was rejected under 35 U.S.C. §103(a) over Fig. 7 in view of Yonezawa and Fetty, and further in view of U.S. Patent No. 5,591,960 (Furukawa). In response, without conceding the correctness of the rejections and solely to advance prosecution, Claim 6 has been cancelled without prejudice to or disclaimer of the subject matter presented therein, and Claim 5 has been amended. Reconsideration and withdrawal of the rejections are respectfully requested.

The present invention concerns an image pickup apparatus which includes a lead of a flexible wiring film, an image pickup element chip electrically connected to the lead at an electrical connection point, and a cover glass for protecting a surface of the image pickup element chip. The lead, image pickup element chip and the cover glass are sealed with a sealant in a peripheral portion of the image pickup element chip. The lead has a hole formed in a portion of the lead in contact with the sealant, the portion of the lead being between the electrical

connection point and an outer end of the lead. A part of this hole is positioned outside the cover glass.

Thus, according to one feature of the invention, a part of the hole is positioned outside the cover glass. By virtue of this feature, it is made easier to decrease the differences in flow rates between sealant flowing on the lead and sealant flowing on other portions. See, for example, page 14, lines 20 to 24, of the present specification.

Fetty, Yonezawa, Furukawa and Applicant's Fig. 7, either alone or in combination, are not seen to teach or suggest at least the foregoing feature.

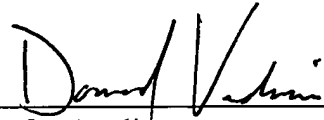
Applicant therefore concludes that the applied documents do not teach or suggest the claimed invention either singly or in the combination proposed by the Office Action, and it is respectfully requested that the Section 103 rejections be withdrawn.

Turning to a formal matter, an Information Disclosure Statement is being submitted herewith, and the Examiner is respectfully requested to consider the document cited therein.

No other matters being raised, the entire application is believed to be fully in condition for allowance and such action is courteously solicited.

Applicant's undersigned attorney may be reached in our Washington, D.C.
office at (202) 530-1010. All correspondence should continue to be directed to our below-listed
address.

Respectfully submitted,



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